Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	01	17.02.2015	1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
06	092	FR4	35	L20.18	P06	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_092_FR4_35_L20.18_p06

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	
	60µ	Prepreg		
Layer-2	18µ	Copper		A1
	200µ	L-FR4		
Layer-3	18µ	Copper		
	60µ	Prepreg		
	60µ	Prepreg		
Layer-4	18µ	Copper		A2
	200µ	L-FR4		
Layer-5	18µ	Copper		
	60µ	Prepreg		
	60µ	Prepreg		
Layer-99	35µ	Copper		

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